ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®	© Co	terial Compo pyright 2005. IPC, Bannoc nternational and Pan-Ameri	kburn, Illinois	s. All rights reserv	tion with lowe	r level	parts, the	declaration	encom	oasses all	lower level mat	erials for whi	if the item is an assembly ch the manufacturer has his declaration.		
1752-2 1.1		Web Site for Informat //www.ipc.org/IPC-1		Form Type * Declaration Class * Distribute Class 6 - RoHS Yes/No, Homogeneous Materials and											
Supplier Information															
Company Name *		Company Unique ID		Unique ID Au	ıthority	Resp	onse Date	*	R	Response Document ID					
RAMI TECHNOLOGY USA L						2016-	-06-30								
Contact Name * Title - Contact				Phone - Contact *			I - Contac	t *		Dunlis	ata Camtaat	> Ath wi	d Danua antativa		
YG Jiao				0755-215371	33	ygjiao@ramitechnology.cor			.com	Duplio	cate Contact	-> Authorize	d Representative		
Authorized Representati	ive *	Title - Representative	Э	Phone - Representative *			l - Represe	entative *	S	upplier Co	mments or UR	L for Addition	nal Information		
Frank Parra				305-593-603	3	frank@ramitechnology.com									
Requester Item Numbe	r	Mfr Item Number		Mfr Item Name	Effecti	ve Date	Version N	Manufacturing Site		Weight *	UOM	Unit Type			
		RSM200S Product F	amily	RSM200S Pr	2021-01-06					133.85	mg	Each			
Alternate Recommenda	Alternate Recommendation						Alternate Item			Comments					
Manufacturing Proces	ss In	formation													
Terminal Plating / Grid Array Material Terminal E			Terminal B	Base Alloy J-STD-020 MSL Rat			ating Peak Process Body			ure Max T	ime at Peak Ten	at Peak Temperature Number of Reflow			
Bright Tin (Sn)			Other		1			26	60 C		10 s	econds 1			
Comments							•			•		!			

Save the fields in this form to a file	Export Data	Import fields from a file into this form	Import Data	Clear all of the fields on this form	Reset Form	Lock the fields on this form to prevent change	Lock Supplier Fields					
RoHS Material Com	position Declaration	ו				Declaration Type *	Simplified					
	PoHS Directive 2002/95/EC ROHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium											
ate that Supplier completes this upplier may have relied on info upplier agrees that, at a minim ritten agreement with respect t	s form. Supplier acknowledges the rmation provided by others in corum, its suppliers have provided c	hat Company will rely on this ce mpleting this form, and that Sup ertifications regarding their cond d conditions of that agreement,	ertification in determining the opplier may not have independentifications to the part, and those	compliance of its products with ently verified such information se certifications are at least as	European Union member state However, in situations where S comprehensive as the certificati	laws that implement the RoHS Direction Supplier has not independently verion in this paragraph. If the Compa	its knowledge and belief, as of the ective. Company acknowledges that fied information provided by others, any and the Supplier enter into a Supplier's liability and the Company's					
RoHS Declaration * 3	- Item(s) does not contain Rol-	IS restricted substances per	the definition above except	for lead in solders and selec	ted exemptions, if any	Supplier Acceptance * Ac	cepted					
xemptions: If the declar bove and choose all appl		RoHS restricted substance	ces per the definition ab	ove except for defined	RoHS exemptions, then se	elect the corresponding resp	oonse in the RoHS Declaration					
Exemption List Version	EL-2006/690/EC											
7a. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).												
Declaration Signat	ure											
·	e all of the required field ed by the Requester) ar	. •		•	-	wn. This will display the s	signature area. Digitally sign					

Supplier Digital Signature YG Jiao

数字签名者: YG Jiao DN: cn=YG Jiao, o=RAMI TECHNOLOGY USA LLC, ou=QA, email=yglio@amillechnology.com, c=CN 日期: 2014.04.08 10:48:35 +08'00'

Homogeneous Material Composition Declaration for Electronic Products

Subltem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem		Homogeneous	Weight	Unit of		Level	Substance Category			Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
	Name		Material	, roigin	Wieasure			Cabotanios Catogory				07.10				-	+	
+1 -1	RSM200S	+M -	MBase	13.65	mg	+C -C	Supplier	Metal Ring	+S	-S	Fe	7439-89-6		2.871	mg			
									+S	-S	Со	7440-48-4		0.025	mg			
									+S	Ş	Mn	7439-96-5		0.02	mg			
									+S	-S	Cr	7440-47-3		0.005	mg			
						+C -C	В	Nickel (external applic	+S	-S	Nickel	7440-02-0		2.03	mg			
						+C -C	Supplier	Glass	+S	-s	SiO2	7631-86-9		2.82	mg			
						+C -C	Supplier	Leads	+S	-S	Fe	7439-89-6		0.992	mg			
									+S	-S	Со	7440-48-4		0.313	mg			
									+S	-S	Mn	7439-96-5		0.001	mg			
						+C -C	В	Nickel (external applic	+S	-S	Nickel	7440-02-0		0.534	mg			
						+C -C	Supplier	Surface Coating	+S	-s	Cu	7440-50-8		0.454	mg			
									+S	-S	Sn	7440-31-0		0.236	mg			
						+C -C	A	Lead/Lead Compound	+S	-S	Lead	7439-92-1	7a. Lead	3.35	mg			
		+M -	M Cover	24.41	mg	+C -C	Supplier	Metal Case	+S	-S	Cu	7440-50-8		13.658	mg			
				•					+S	-s	Mn	7439-96-5		0.028	mg			
									+S	-S	Fe	7439-89-6		0.002	mg			
									+S	-S	Zn	7440-66-6		3.938	mg			
						+C -C	В	Nickel (external applic	+S	-S	Nickel	7440-02-0		6.784	mg			
		+M -	M Quartz Crystal	5.25	mg	+C -C	Supplier	Quartz Blank	+S	-S	SiO2	7631-86-9		2.36	mg			
						+C -C	Supplier	Blank Metalization	+S	-S	Cr	7440-47-3		0.004	mg			
									+S	-S	Ag	7440-22-4		0.03	mg			
						+C -C	Supplier	Solder	+S	-s	Ag	7440-22-4		0.06	mg			
									+S	-S	Sn	7440-31-5		0.23	mg			

			+C	CA	Lead/Lead Compound	+S	-S	Lead	7439-92-1	7a. Lead	2.57	mg	
+M -M Plastic Mold	76.8	mg	+C	CSupplier	Epoxy compound		-S	SiO2	7631-86-9		54.528	mg	
	•			_	•	+S	-S	Epoxy Resin	Trade segg		7.68	mg	
						+S	-S	Phoenol Resin	Trade segg		7.286	mg	
						+S	-S	Flame Retardent	1332-07-6		3.84	mg	
						+S	-S	Pigment	01333-86-4		1.93	mg	
						+S	-S	Coupling Agent	2530-83-8		1.536	mg	
+M -M Lead Franme	13.73	mg	+C	CSupplier	Metal Frame	+S	-S	Cu	7440-50-8		8.402	mg	
						+S	-S	Zn	7440-66-6		4.328	mg	
			+C	CSupplier	Surface coating	+S	-S	Sn	7440-31-5		0.858	mg	
						+S	-S	Cu	7440-50-8		0.143	mg	